



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo O-1875 P

Oleic Acid 75% Plus

Product Data Sheet

CAS No. 67701-08-0

EINECS No. 266-932-7

Parameter	Unit	Specification
Appearance at 30 Deg. C	-	Pale yellow liquid, free of foreign matter
Colour, Lovibond, Max	In 5,1/4" Cell	Y=8.0; R=1.0
Acid Value	mg KOH/Gm	195-205
Sap. Value	mg KOH/Gm	196-206
Iodine Value	Gms I2 / 100 Gms	90.0 – 105.0
Cloud point	° C	8.0 Max

Fatty Acid Composition	Unit	Specification
Up to C 18 (Saturated)	% by GC	12.0 Max
C 18:1	% by GC	75.0 Min
C 18:2	% by GC	18.0 Max
Others	% by GC	1.0 Max

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Food ingredients, esters, surfactants, transparent soaps, cosmetics and personal care products. Lubricants, metallic soaps, coatings and adhesives.

PACKING

Available in standard 180kg MS/HDPE drums, IBC containers or flexi bags, Bulk ISO container loads. Customised packing size can be made available upon request.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157

Evyap Sabun Malaysia Sdn Bhd

PL0 70, Jalan Nibong 4, Tanjung Langsat Industrial Complex, 81700 Pasir Gudang, Johor Darul Takzim, Malaysia.

Telephone: +607 252 7000; Fax: +607 252 0777,

Website: www.evyapoleo.com

E-mail: ESMSales@evyap.com.tr

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